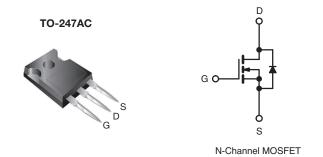


### Power MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	200				
R <sub>DS(on)</sub> (Ω)	V <sub>GS</sub> = 10 V 0.055				
Q <sub>g</sub> (Max.) (nC)	230				
Q <sub>gs</sub> (nC)	42				
Q <sub>gd</sub> (nC)	110				
Configuration	Single				



#### **FEATURES**

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



#### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247AC package is preferred commercial-industrial applications where higher power levels preclude the use of TO-220AB devices. The TO-247AC is similar but superior to the earlier TO-218 package because of its isolated mouting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.

ORDERING INFORMATION			
Package	TO-247AC		
Lead (Pb)-free	IRFP260PbF		
Lead (Fb)-liee	SiHFP260-E3		
SnPb	IRFP260		
OIII D	SiHFP260		

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unle	ss otherwise	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	200	.,,	
Gate-Source Voltage			$V_{GS}$	± 20	V	
Continuo Dunio Comment	\/ -+ 10\/	T <sub>C</sub> = 25 °C		46		
Continuous Drain Current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	29	Α	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	180	1	
Linear Derating Factor				2.2	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	1000	mJ	
Repetitive Avalanche Currenta			I <sub>AR</sub>	46	А	
Repetitive Avalanche Energy <sup>a</sup>			E <sub>AR</sub>	28	mJ	
Maximum Power Dissipation $T_C = 25  ^{\circ}C$			$P_{D}$	280	W	
Peak Diode Recovery dV/dt <sup>c</sup>			dV/dt	5.0	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	- °C	
Soldering Recommendations (Peak Temperature) for 10 s			-	300 <sup>d</sup>		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b.  $V_{DD}=50$  V, starting  $T_J=25$  °C, L=708  $\mu H,~R_g=25$   $\Omega,~I_{AS}=46$  A (see fig. 12). c.  $I_{SD}\leq46$  A, GI/GI GI/

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	40		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.24	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.45		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static					•	•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$	V, I <sub>D</sub> = 250 μA	200	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	o 25 °C, I <sub>D</sub> = 1 mA	-	0.24	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V$	<sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub>	S = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	l	V <sub>DS</sub> = 20	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V		-	25	
Zero Gate voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 160 V, V	<sub>'GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 28 A <sup>b</sup>	-	-	0.055	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 5	0 V, I <sub>D</sub> = 28 A <sup>b</sup>	24	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	V	<sub>GS</sub> = 0 V,	-	5200	-	pF
Output Capacitance	C <sub>oss</sub>	V	$_{0S} = 25 \text{ V},$	-	1200	-	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0 I	MHz, see fig. 5	-	310	-	
Total Gate Charge	$Q_g$	V <sub>GS</sub> = 10 V		-	-	230	nC
Gate-Source Charge	$Q_{gs}$			-	-	42	
Gate-Drain Charge	$Q_{gd}$			-	-	110	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 100 V, $I_{D}$ = 46 A, $R_{g}$ = 4.3 $\Omega$ , $R_{D}$ = 2.1 $\Omega$ , see fig. 10 <sup>b</sup>		-	23	-	ns
Rise Time	t <sub>r</sub>			-	120	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	100	-	
Fall Time	t <sub>f</sub>			-	94	-	
Internal Drain Inductance	$L_{D}$	Between lead, 6 mm (0.25") from package and center of die contact		-	5.0	-	-11
Internal Source Inductance	L <sub>S</sub>			_	13	-	- nH
Drain-Source Body Diode Characteristic	s				•	•	
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	46	- A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	180	
Body Diode Voltage	$V_{SD}$	$T_J = 25  ^{\circ}\text{C},  I_S = 46  \text{A},  V_{GS} = 0  \text{V}^{\text{b}}$		-	-	1.8	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	- T <sub>J</sub> = 25 °C, I <sub>F</sub> = 46 A, dl/dt = 100 A/μs <sup>b</sup>		-	390	590	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	4.8	7.2	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and				LD)	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

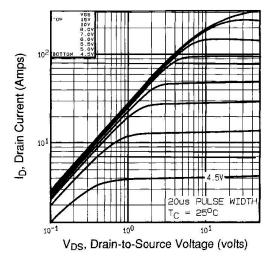
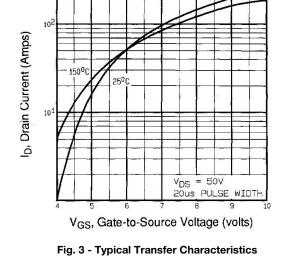


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C



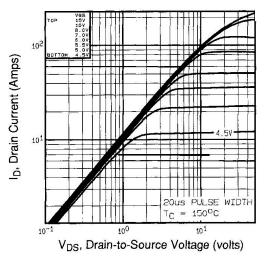


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 150 °C

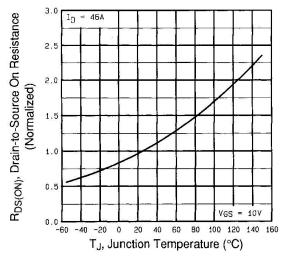


Fig. 4 - Normalized On-Resistance vs. Temperature



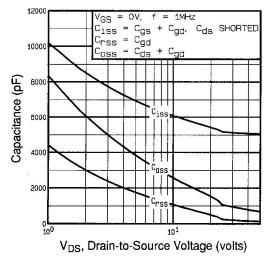


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

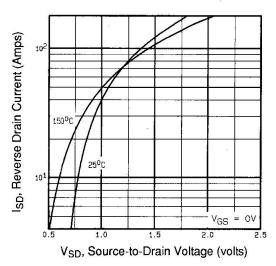


Fig. 7 - Typical Source-Drain Diode Forward Voltage

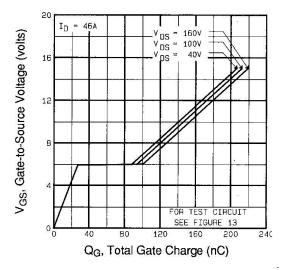


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

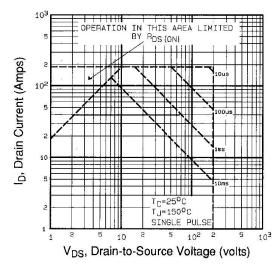


Fig. 8 - Maximum Safe Operating Area





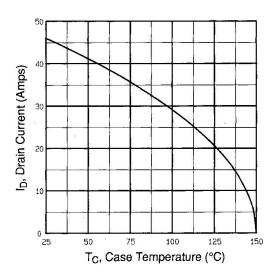


Fig. 9 - Maximum Drain Current vs. Case Temperature

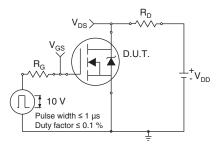


Fig. 10a - Switching Time Test Circuit

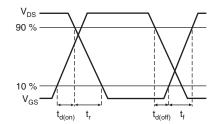


Fig. 10b - Switching Time Waveforms

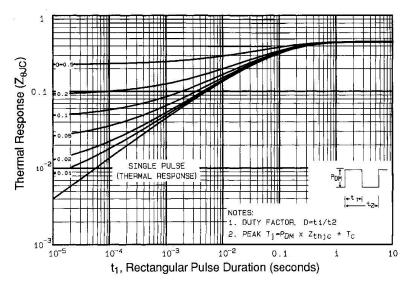
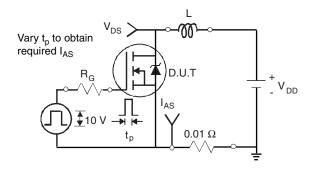


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case





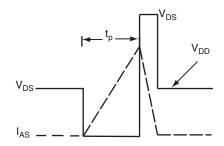


Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

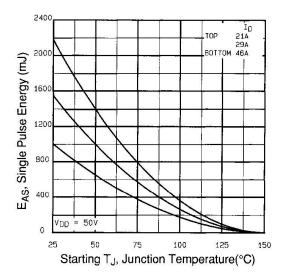


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

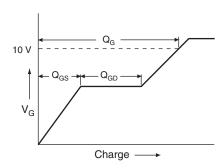


Fig. 13a - Basic Gate Charge Waveform

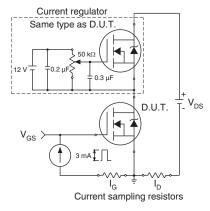
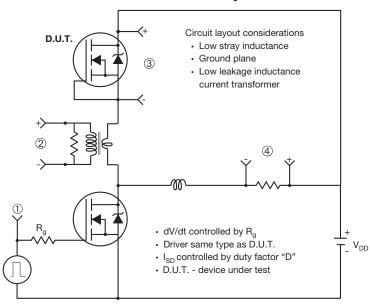


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



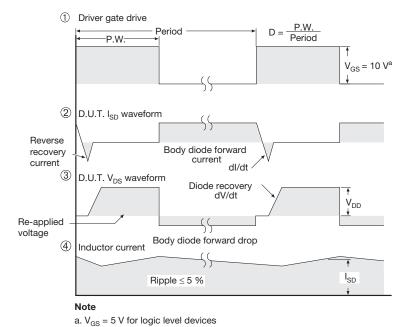
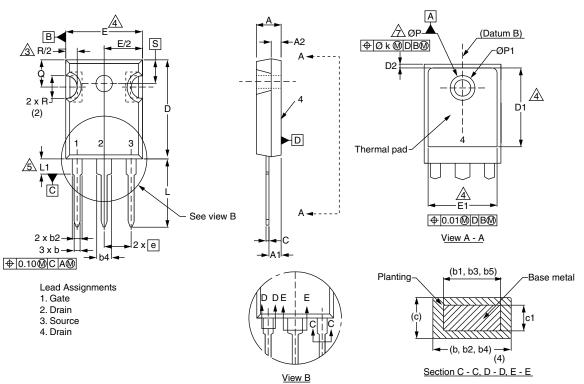


Fig. 14 - For N-Channel

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# **TO-247AC (High Voltage)**



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	
E1	13.72	ı	0.540	ı	
е	5.46	BSC	0.215 BSC		
Øk	0.2	0.254		0.010	
L	14.20	16.25	0.559	0.640	
L1	3.71	4.29	0.146	0.169	
N	7.62 BSC		0.300 BSC		
ØΡ	3.51	3.66	0.138	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217	BSC	
0.217 800					

ECN: X13-0103-Rev. D, 01-Jul-13

DWG: 5971

#### **Notes**

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
  5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.





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